

SOT618-2

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN40 |
| Package type industry code | HVQFN40 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-220 |
| Mounting method type | S (surface mount) |
| Issue date | 22-4-2003 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|------|-----|------|
| D | package length | 5.9 | - | 6 | 6.1 | mm |
| E | package width | 5.9 | - | 6 | 6.1 | mm |
| A | seated height | [tbd] | - | 0.85 | 1 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 40 | - | |

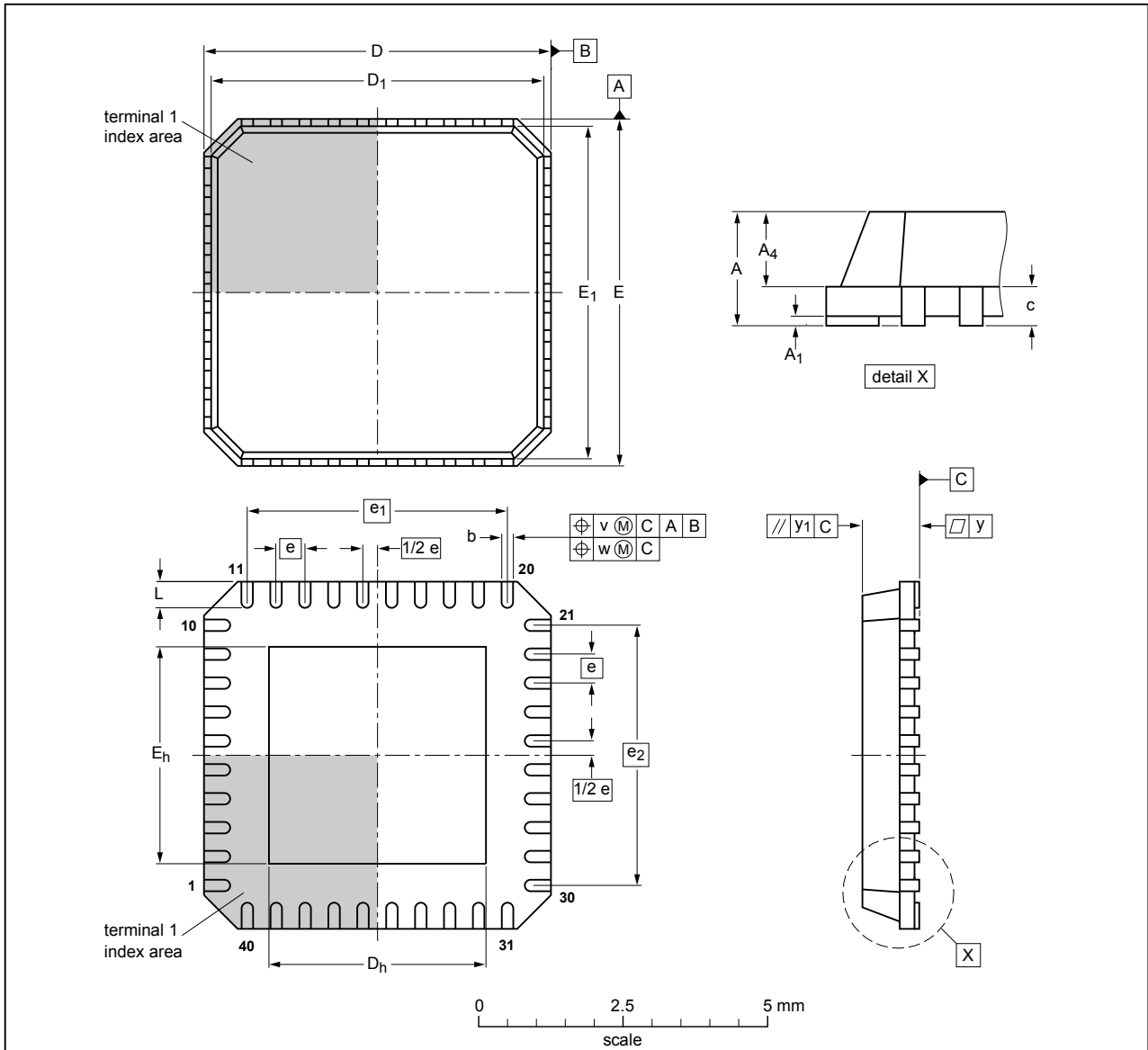


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2. Package outline

HVQFN40: plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₄ | b | c | D | D ₁ | D _h | E | E ₁ | E _h | e | e ₁ | e ₂ | L | v | w | y | y ₁ |
|------|--------|----------------|----------------|--------------|-----|------------|----------------|----------------|------------|----------------|----------------|-----|----------------|----------------|------------|-----|------|------|----------------|
| mm | 1 | 0.05 0.00 | 0.80 0.65 | 0.30 0.18 | 0.2 | 6.1 5.9 | 5.8 5.7 | 4.4 4.2 | 6.1 5.9 | 5.8 5.7 | 4.4 4.2 | 0.5 | 4.5 | 4.5 | 0.5 0.3 | 0.1 | 0.05 | 0.05 | 0.1 |

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|--------|-------|--|---------------------|------------|
| | IEC | JEDEC | JEITA | | | |
| SOT618-2 | --- | MO-220 | --- | | | 03-04-22 |

Fig. 1. Package outline HVQFN40 (SOT618-2)

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3. Soldering

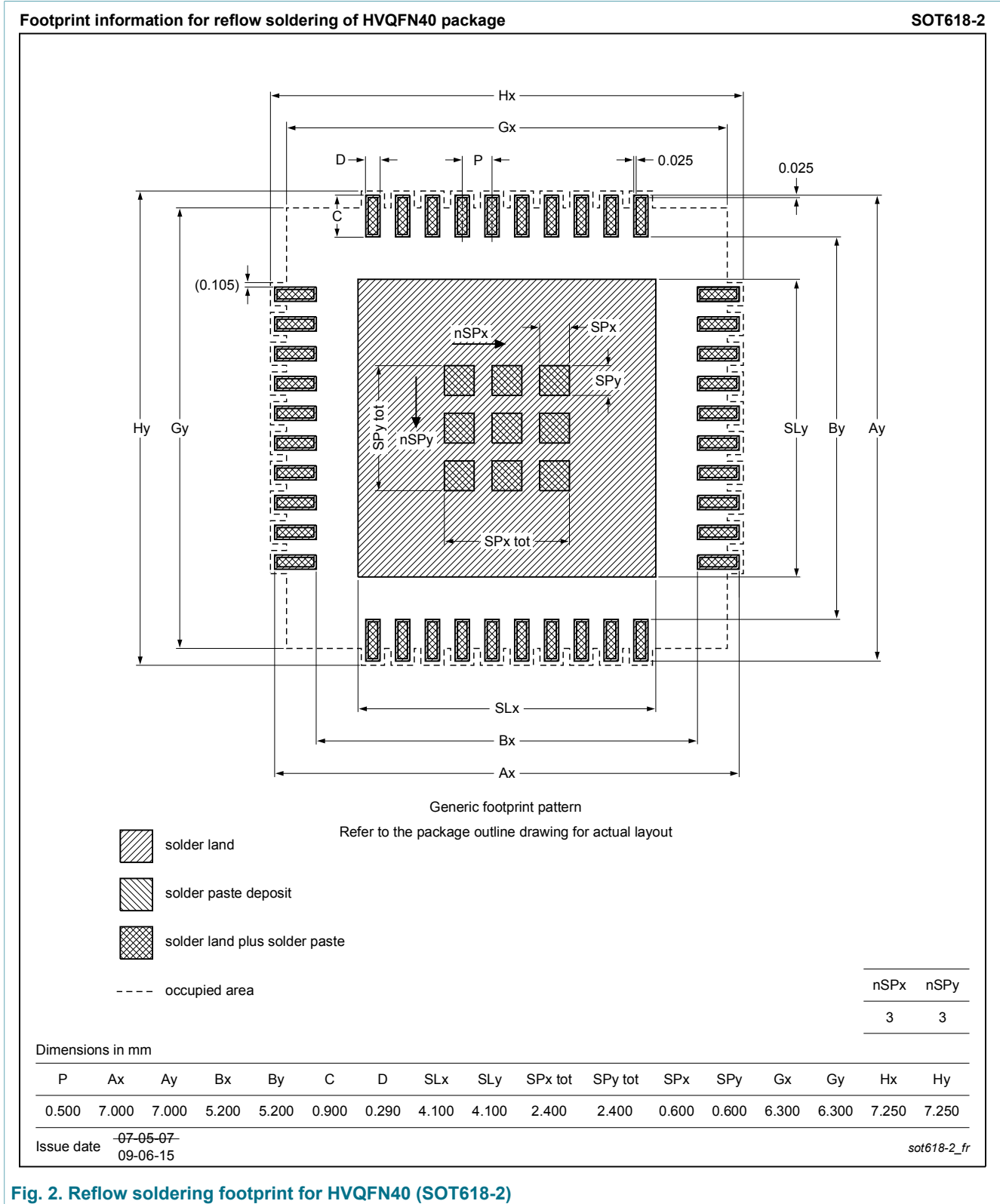


Fig. 2. Reflow soldering footprint for HVQFN40 (SOT618-2)

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4. Legal information

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Date of release: 8 February 2016
